

INVESTOR RELATIONS

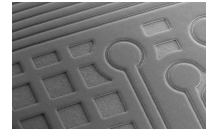
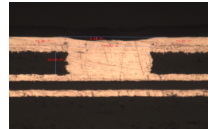
1Q.2020 YMT IR BOOK

Your Most trustworthy



Total Solution for Customer

YMT possesses specialty chemical technologies applicable to the entire process including cleaning, etching, and finish plating



Final Finishing Chemical

Soft ENIG Process

- ✓ CF 300 Series
- ✓ MIKO Series

ENIG Process

- ✓ PEN Series
- ✓ MIKO Series

ENEPIG Process

- ✓ PEN Series
- ✓ ELP or ZEP Series
- ✓ IR Gold Series

EPIG process

- ✓ ZEP Series
- ✓ IR Gold Series

Immersion process

- ✓ PROTIN Series

Electrolytic gold process

- ✓ HG 300 series
- ✓ SAU 10 series

Copper plating chemical

Electroless Copper plating

- ✓ HVF Series
- ✓ MJH series

Electrolytic Copper plating

- ✓ BJ series
- ✓ HBJ Series(Half-fill)
- ✓ FSBJ Series(Flash plating)
- ✓ ZEUS Series(Via-fill)

Process Chemical

DES Chemical

- ✓ MSAP/SAP DFR Stripper
- ✓ MSAP/SAP Cu seed Etchant
- ✓ GMZ Series
- ✓ HWA Series

Cleaner

- ✓ FXC Series
- ✓ EQ Series

Gold Recover

UBM Etchant

LAZ Process

New product for 5G

No etching and roughness laminating pretreatment

Ultra low profile detachable thin copper foil

Positive Cu roughening Process Nanotus®

Electroless Copper plating for LCP

2020 Business Overview

New business area
Existing business area

		Existing business area		New entry					
		FPCB, RFPCB		PKG		HDI		RIGID	
Major player	Domestic	<ul style="list-style-type: none"> SEMCO BH Flex Youngpoong Daeduck 	<ul style="list-style-type: none"> SEMCO Daeduck SIMTECH Korea Circuit 	<ul style="list-style-type: none"> Daeduck LG Innoteck Korea Circuit 	<ul style="list-style-type: none"> Hyunwoo SEIL 				
	Global	<ul style="list-style-type: none"> Zhending Technology Career Unimicron Mektron 	<ul style="list-style-type: none"> AT&S Zhending Technology Ibiden 	<ul style="list-style-type: none"> AT&S Zhending Technology Ibiden 	<ul style="list-style-type: none"> Various 				
Process Chemical		<ul style="list-style-type: none"> Expanding market share Promotions chemicals for fine pattern 	<ul style="list-style-type: none"> Entering the market with the first sales to major customers in the 2nd half of 2019 	<ul style="list-style-type: none"> Increasing sales related to stripping/etching chemicals. 	<ul style="list-style-type: none"> - 				
	Cu Plating	무전해	<ul style="list-style-type: none"> High domestic share (Estimate at least 40%) 	<ul style="list-style-type: none"> First sales in 1Q of 2020 	<ul style="list-style-type: none"> Gain a high level of market share within the S company. 	<ul style="list-style-type: none"> - 			
		전기용	<ul style="list-style-type: none"> New Business area - 100% foreign production share 	<ul style="list-style-type: none"> Promotion for customer 	<ul style="list-style-type: none"> Developing 	<ul style="list-style-type: none"> - 			
	Finish Plating	Electroless	<ul style="list-style-type: none"> Global Top market share more than 50% 	<ul style="list-style-type: none"> Test by customer 	<ul style="list-style-type: none"> Developing 	<ul style="list-style-type: none"> Selling to some domestic and Chinese customer 			
		Electro	<ul style="list-style-type: none"> Developing 	<ul style="list-style-type: none"> Developing 	<ul style="list-style-type: none"> Developing 	<ul style="list-style-type: none"> Developing 			

2020 Business Overview

Market Review

- Continuous increase in RFPCB production for camera modules
- Increasing OLED adoption models of North American and Chinese smartphone makers
- Korean PKG substrate's economic boom are highly expected
- There's a risk for sales reduction of Smartphone because of COVID 19 globally.

	Finish Plating(Gold Plating)	Copper Plating Chemical	Process Chemical	Outsourcing & New Business
Domestic	<ul style="list-style-type: none"> ✓ <u>Korean FPCB manufacturer's output increases due to increased OLED-mounted models.</u> ✓ Increased chemical consumption due to increased camera modules in Korea ✓ Attempts to enter the gold-plated market of PKG Substrates beyond the FPCB 	<ul style="list-style-type: none"> ✓ Increase the volume of copper plating (MJH series) with OLED RFPCB ✓ <u>Entering the Via-fill electric copper plating market for FPCB, RFPCB</u> ✓ <u>Electroless copper plating chemical launching for PKG substrates</u> 	<ul style="list-style-type: none"> ✓ Enhance promotion of circuit-process chemicals for fine circuit patterns in FPCB and RFPCB ✓ <u>Expansion of PKG substrates chemicals for various domestic customer.</u> 	<ul style="list-style-type: none"> ✓ Maintaining outsourcing sales of PCB for camera modules (YPT) ✓ Increasing outsourcing sales of Via-fill electrostatic copper plating (YPT) ✓ <u>Promote 5G EMI Shield for domestic Smartphone Brand.</u>
Global	<ul style="list-style-type: none"> ✓ <u>ENEPIG volume is increased according to the expansion of camera modules by Chinese local customers</u> ✓ Growth in sales due to operating rate of local customers in Vietnam and the expansion of relocation of Korean companies 	<ul style="list-style-type: none"> ✓ Expand sales of electroless copper plating in the Vietnamese market (SEMCO, BH, etc.) ✓ Launching and local manufacturing of copper plating chemicals in China at the end of 2020 	<ul style="list-style-type: none"> ✓ Promotion of circuit process chemicals for Vietnamese and Chinese local companies 	<ul style="list-style-type: none"> ✓ Promote 5G EMI Shield materials for Chinese local companies, supply after NDA contract with a Chinese local company ✓ Expanded outsourcing sales of gold-plating for FPCB in Vietnam

2020 CAPEX Major Schedule

Ultra-thin copper foil manufacturing facility extension

- EMI Shield materials: Supplying to Korean S company's customers and attracted large attentions from China.
- Primary extension scale : 70,000m² per month / Insufficient Capa because of the co-using RTR outsourcing currently.
- Area : Ansan, Gyeonggi Province, Korea
- Primary investment scale : about 3 billion won

Establishment of a Chemical Manufacturing Plant in China

- A weak share in general chemical market compared to the high-priced market in China.
- Higher price competitiveness in general chemical market through production/sales in China, local production of copper-plated chemical materials with high demand
- Area : securing about 13,000m² of land in Zhuhai and began building the plant within the year.
- Total investment scale : about 7 billion won

Expansion of plating line in Vietnam

- The estimate of the increase in outsourcing sales in Vietnam due to its transfer of domestic customer's production base
- Finished setting-up 2 gold plating lines. 1 line is currently in setting.
- Considering additional plating lines due to its demand of local outsourcing
- Additional investment scale : about 2 billion won

Expansion of Chemical Manufacturing Facility for PKG

- An increase in supplying size of chemicals for PKG's is expected.
- Operating small clean rooms and manufacturing facilities now.
- Considering expanding clean rooms and facilities due to its demand.
- Additional investment scale : about 3 billion won

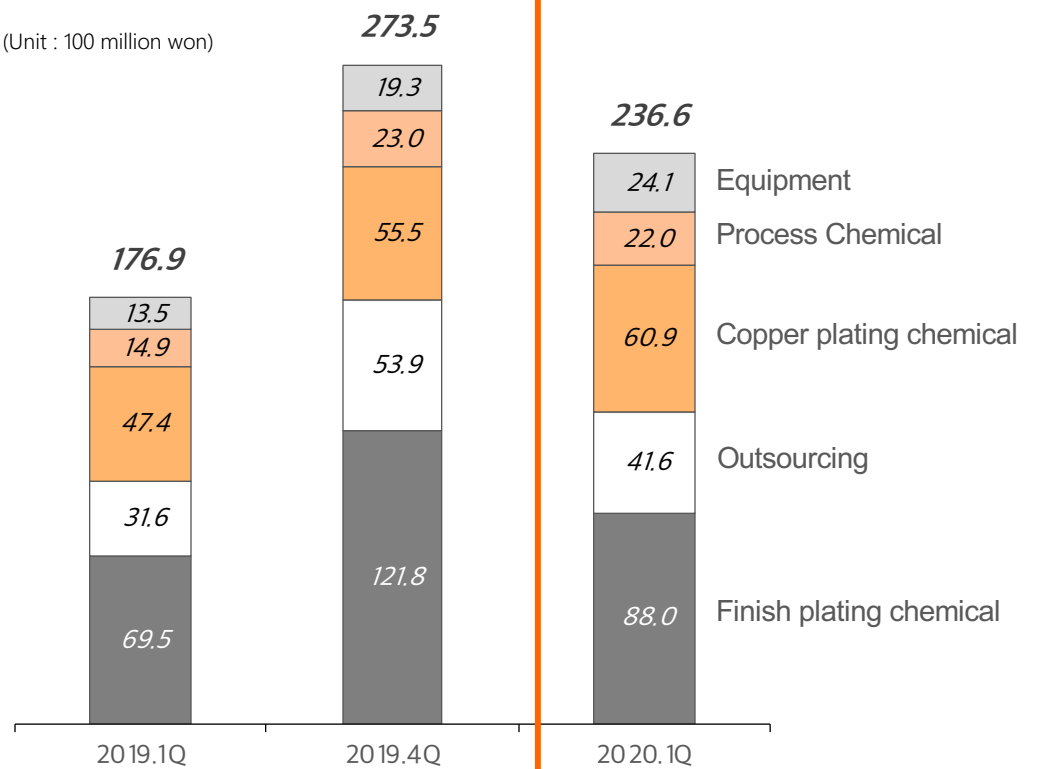
Review and Expectation

	Review for 1Q.2020	Expectation for 2Q.2020
<i>Final finishing chemical</i>	<ul style="list-style-type: none"> Increasing sales in Chinese local market because of camera module chemical process. Benefit from Galaxy series to Korean and Vietnam market. 	<ul style="list-style-type: none"> Every 2Q is a traditional off-season for launching a brand-new smartphone. So, less production for PCB Increase sales in Chinese market for mid-end smartphone of Apple
<i>Copper plating chemical</i>	<ul style="list-style-type: none"> Market share expansion for FPCB customer in Korea and Vietnam Testing for PKG substrate line Benefit from "Air Pod" RF PCB. 	<ul style="list-style-type: none"> 2Q is a traditional off-season for launching a brand-new smartphone. Wireless headset PCB can cover some amount of sales reduction for smartphone PCB. Promotion for PKG Substrate customer.
<i>Process Chemical</i>	<ul style="list-style-type: none"> Etching / Dry film remover chemical sales expansion for PKG substrate customer. 	<ul style="list-style-type: none"> Etching / Dry film remover chemical sales expansion for PKG substrate customer.
<i>PCB plating outsourcing</i>	<ul style="list-style-type: none"> Continuous sales for Camera module plating. Sales expansion for Via Fill process Delay sales in Vietnam outsourcing because of COVID 19. 	<ul style="list-style-type: none"> Camera module plating will be reduced slightly compare to last quarter. Via-Fill plating expect
<i>Copper foil & Equipment</i>	<ul style="list-style-type: none"> Copper foil : Adopted for Clamshell type foldable smartphone antenna part as a EMI Shield. 	<ul style="list-style-type: none"> Promotion for 5G EMIG Shield for Korean and Chinese customer.

Sales Result

- Final Finishing chemical
- Copper plating chemical
- Equipment / etc.
- Plating Outsourcing
- Process Chemical

(Unit : 100 million won)



- **Increasing sales YoY 133.7%**
 - ✓ The biggest sales on 1Q in history.
- **Increasing Sales on all divisions. (YoY)**
 - ✓ Finish plating chemical : High sales increase in Chinese market because of increasing number of camera module.
 - ✓ Copper plating chemical : Market share expansion in Korean and Vietnam market.
 - ✓ Process Chemical : Sales expansion for PKG substrate customer.
- **Less PCB production quantity compare to 4Q.2019**
 - ✓ Less sales Samsung's flagship smartphone
 - ✓ Less production RFPCB for OLED model.

Income Statement

(Unit : 100 million won)

	1Q.2020	ratio	1Q.2019	ratio
I . Sales	236.6	100%	176.9	100%
II . Cost of sales	157.4	66.5%	112.8	63.8%
III . Gross profit	79.2	33.5%	64.1	36.2%
Sales and administrative expenses	38.6	16.3%	30.5	17.3%
IV . Operating income	40.6	17.2%	33.6	19.0%
Finance income	16.7	7.1%	4.7	2.7%
Finance costs	6.0	2.6%	2.6	1.5%
Other gains	0.3	0.1%	2.5	1.4%
Other losses	1.0	0.4%	0.3	0.2%
Losses on equity method	-0.5	-0.2%	0.1	0.1%
V . Profit before tax	50.1	21.2%	38.0	21.5%
Income tax expense	11.5	4.9%	4.8	2.7%
VI . Profit	38.6	16.3%	33.2	18.7%

Profitability Indicator

	1Q.2020	1Q.2019
Operating income ratio	17.2%	19.0%
Net profit ratio	16.3%	18.7%
EBITDA (Margin rate)	54.6 (23.1%)	43.2 (24.4%)
ROE	3.7%	3.8%
Total asset turnover	14.3%	13.6%

Balance Sheet

(Unit : 100 million won)

	1Q.2020	2019
Assets		
Cashable assets	435.1	417.5
Trade receivable	263.6	264.7
Tangible assets	620.3	608.6
Other assets	347.6	348.5
Total assets	1,666.6	1,639.3
Liabilities		
Trade payables	38.5	33.0
Borrowings	324.5	344.7
Convertible bond	143.3	140.4
Other liabilities	206.3	216.9
Total liabilities	712.6	735.0
Equity		
Issued capital	37.0	37.0
Capital surplus	218.6	218.6
Retained earnings	560.9	531.3
Other equity	137.5	117.4
Total equity	954.0	904.3
Total equity and liabilities	1,666.6	1,639.3

Cash Flow

(Unit : 100 million won)

	1Q.2020	1Q.2019
Cash at begging of period	417.5	276.1
Cash flows from operating activities	50.0	25.0
Net profit	38.6	33.2
Depreciation	13.9	9.6
Interest cost	5.2	2.4
Corporate tax	11.5	4.8
Gain on foreign currency translation	(12.7)	(3.8)
etc	7.2	(19.6)
Cash flows from investing activities	(19.1)	(25.0)
Purchase of a tangible asset	(17.1)	(26.1)
Cash flows from financing activities	(21.8)	18.9
Proceeds of borrowings	(20.1)	18.9
Net increase cash flow	9.1	18.9
Effect of exchange rate changes	8.5	5.7
Cash at end of period	435.1	300.7

END OF DOCUMENT

Thank you